



Plasma-Therm



**ADVANCED
VACUUM**
A Plasma-Therm Company

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Plasma-Therm Technical Workshop: Fundamentals of Plasma Processing (Etching and Deposition)

When: 14 April 2016 (Thursday), 8:30am to 5:00pm

Location: Politecnico di Milano

Dipartimento di Elettronica, Informazione e Bioingegneria

Via Ponzio, 34/5 – 20133 – Milano (MI)

Building 20 Conference Room

The workshop will focus on the fundamentals of plasma etching and deposition. Lectures will include the basics of plasma reactors and mechanisms for etching and deposition and review state-of-the-art etching and deposition technologies as applied to semiconductors, MEMS, and nanofabrication. Talks will cover compound semiconductor, dielectric, and deep silicon etching as well as PECVD and high density plasma CVD of silicon based materials. Fundamental and new ideas for endpoint detection and sample thermal budget management will be presented.



Event is free. Pre-registration requested before April 12, 2016

For general and registration enquiries, please contact:

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Objectives

- Learn the fundamentals of plasma, reactors, and etching mechanisms
- Review etching technologies for deep silicon etching, compound semiconductors, and dielectrics
- Provide essentials of PECVD and HDPCVD
- Explore the fundamentals and new ideas in endpoint detection
- Understand thermal budget considerations

Program

8:00am	Registration (light breakfast courtesy of Plasma-Therm)
8:30 am	Welcome
8:45 am	Basics: Plasma, Reactors, and Etching Mechanisms
10:45 am	Break
11:00 am	Dielectric Etching
12:00 pm	Networking Lunch (Courtesy of Plasma-Therm)
1:00 pm	Compound Semiconductor Etching
2:00 pm	Deep Reactive Ion Etching of Silicon
2:45 pm	Break
3:00 pm	Endpoint Basics
3:30 pm	Thermal Budget Management
4:00 pm	PECVD and HDP CVD (high density plasma CVD)
5:00 pm	Conclusion (Note: Q&A will be encouraged during the talks)

Speaker information follows



Speaker Information: David Lishan, Ph.D.

After receiving his undergraduate degree in Chemistry from UC Santa Cruz and Ph.D. from UC Santa Barbara in Solid State Electrical Engineering he has worked and published on a wide range of material, semiconductor, and chemistry R&D projects in the areas of lithography, photochemistry, x-ray mask fabrication, PVD, and plasma processing. During his 17 years at Plasma-Therm, he has had business unit management and worldwide marketing responsibilities as well as managing the development of recently released plasma dicing product. Currently he is in the roles of Principal Scientist and Director in Technical Marketing, and recently organized and presented plasma processing workshops at leading institutions throughout the world. His primary focus is on the application of plasma processing for R&D, MEMS, photonics, data storage, power, and compound semiconductor applications. He holds two patents in the area of semiconductor processing and has over 60 publications and conference presentations.

With Plasma-Therm, he has organized and presented plasma processing workshops at leading institutions throughout the world, including Harvard University, UC Berkeley, University of Notre Dame, UC Los Angeles (UCLA), University of South Florida, Stanford University, Lund University (Sweden), IMRE (Singapore), UC Santa Barbara (UCSB), ISCAS (Beijing, China), SINANO (Suzhou, China), Shanghai Jiao Tong University, UT Austin, Cornell University, Pennsylvania State University, KANC (S. Korea), University of Alberta, Weizmann Institute, University of Queensland, University of New South Wales, and in Israel.